

8551 AVAILABLE COPY

(54) HYBRID INTEGRATED CIRCUIT DEVICE

(11) 62-126661 (A) (43) 8.6.1987 (19) JP

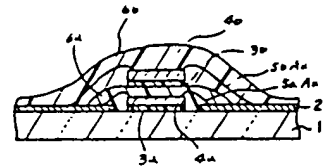
(21) Appl. No. 60-267712 (22) 27.11.1985

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(51) Int. Cl. H01L25/04, H01L21/60

**PURPOSE:** To obtain a high-density, compact hybrid integrated circuit device, by mounting semiconductor pellets not in a planar arrangement but in a stacked state in two layers through resin.

**CONSTITUTION:** On an insulating substrate 1, on which a wiring conductor 2 is formed, a semiconductor pellet 4 is mounted with a bonding resin 3a. The electrode of the semiconductor pellet 4a and the wiring conductor 2 are bonded with an Au thin wire 5a. Then the semiconductor pellet 4a and the Au thin wire 5a are coated with a coating resin 6a. Thereafter, another semiconductor pellet 4b is mounted on the coating resin 6a, which is coated on the previously provided semiconductor pellet 4a with a bonding resin 3b. Then the pellet is connected with an Au thin wire 5b by the similar way as before. Thereafter, the entire body is coated with a coating resin 6b, and a hybrid integrated circuit device is completed.



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